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67,200-409; TSMC 00-661  
Serial Number 09/978,420

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TO: Commissioner for Patents  
P.O. Box 1450  
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FROM: Tung & Associates  
838 West Long Lake Road - Suite 120  
Bloomfield Hills, MI 48302

DATE: 6 July 2003

REF: Applicant : Chou et al                      Filing Date : 15 October 2001  
Serial No : 09/978,420                      Att'y No. : 67,200-409  
Art Unit : 2815                      Examiner : N Drew Richards  
Title : Microelectronic Fabrication With Upper Lying Aluminum  
Fuse Layer in Copper Interconnect Semiconductor Technology  
and Method for Fabrication Thereof

AMENDMENT AND RESPONSE TO OFFICE ACTION

Sir:

In response to an office action mailed on 16 May 2003, please consider the following amendments and remarks pertaining to the above referenced application.

There are no amendments to the specification or the drawings. Amendments to the claims are found within the Listing of the Claims that begins on page 2 of this paper. Remarks begin on page 4 of this paper.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Commissioner for Patents, POB 1450, Alexandria, VA 22313 on July 11, 2003.

Kathy Dixon